

SGM40561 High Input Voltage Single Cell Charger

GENERAL DESCRIPTION

The SGM40561 is a fully integrated high input voltage single-cell Li-lon battery charger. The charger uses a CC/CV charge profile required by Li-lon battery. The charger accepts an input voltage up to 26.5V but is disabled when the input voltage exceeds the OVP threshold, typically 10.5V, to prevent excessive power dissipation. The 26.5V rating eliminates the over-voltage protection circuit required in a low input voltage charger.

The charge current and the full-of-charge (FOC) current are programmable with external resistors. When the battery voltage is lower than typically 2.55V (SGM40561-4.2), 2.62V (SGM40561-4.3) or 2.65V (SGM40561-4.35), the charger preconditions the battery with typically 19% of the programmed charge current. When the charge current reduces to the programmable FOC current level during the CV charge phase, an FOC indication is provided by the CHG pin, which is an open-drain output. An internal thermal foldback function protects the charger from any thermal failure.

Two indication pins (\overrightarrow{PPR} and \overrightarrow{CHG}) allow simple interface to a microprocessor or LEDs. When no adapter is attached or when disabled, the charger draws less than 1µA leakage current from the battery.

The SGM40561 is available in Green TDFN-2×2-8L package and is rated over the -40°C to +85°C temperature range.

FEATURES

- 4.2V/4.3V/4.35V Charge Voltage
- 5mA to 200mA Charger for Tiny Cell Li-lon or Polymer Batteries
- Integrated Pass Element and Current Sensor
- No External Blocking Diode Required
- Low Component Count
- Programmable Charge Current
- Programmable Full-of-Charge Current
- Charge Current Thermal Foldback Protection
- 2.55V/2.62V/2.65V Trickle Charge Threshold
- 10.5V Input Over-Voltage Protection
- 26.5V Maximum Voltage Power Input
- Power Presence and Charging Indications
- Less than 1µA Leakage Current off the Battery When No Input Power Attached or Charger Disabled
- Available in Green TDFN-2×2-8L Package

APPLICATIONS

IOT Gadgets Wearable Devices Credential Keys Wireless Remote



PACKAGE/ORDERING INFORMATION

MODEL	V _{сн} (V)	PACKAGE DESCRIPTION	SPECIFIED TEMPERATURE RANGE	ORDERING NUMBER	PACKAGE MARKING	PACKING OPTION
	4.2	TDFN-2×2-8L	-40°C to +85°C	SGM40561-4.2YTDE8G/TR	SZD XXXX	Tape and Reel, 3000
SGM40561	4.3	TDFN-2×2-8L	-40°C to +85°C	SGM40561-4.3YTDE8G/TR	SX7 XXXX	Tape and Reel, 3000
	4.35	TDFN-2×2-8L	-40°C to +85°C	SGM40561-4.35YTDE8G/TR	SX4 XXXX	Tape and Reel, 3000

NOTE: XXXX = Date Code.

Green (RoHS & HSF): SG Micro Corp defines "Green" to mean Pb-Free (RoHS compatible) and free of halogen substances. If you have additional comments or questions, please contact your SGMICRO representative directly.

ABSOLUTE MAXIMUM RATINGS

VIN to GND0.3V to 30V
\overline{PPR} , \overline{CHG} , \overline{EN} , IMIN, IREF, BAT to GND0.3V to 6V
Storage Temperature Range65°C to +150°C
Package Thermal Resistance
$TDFN-2\times2-8L,\theta_{JA}118^\circ C/W$
Junction Temperature+150°C
Lead Temperature (Soldering 10 sec)+260°C
ESD Susceptibility
HBM4000V
MM200V
CDM

RECOMMENDED OPERATING CONDITIONS

Supply Voltage Range	4.55V to 9.35V
Maximum Supply Voltage	
Programmed Charge Current	5mA to 200mA
Operating Temperature Range	-40°C to +85°C

OVERSTRESS CAUTION

Stresses beyond those listed may cause permanent damage to the device. Functional operation of the device at these or any other conditions beyond those indicated in the operational section of the specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

ESD SENSITIVITY CAUTION

This integrated circuit can be damaged by ESD if you don't pay attention to ESD protection. SGMICRO recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage. ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

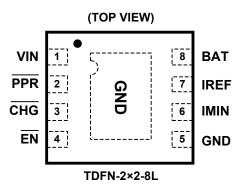
DISCLAIMER

SG Micro Corp reserves the right to make any change in circuit design, specification or other related things if necessary without notice at any time.



SGM40561

PIN CONFIGURATION



PIN DESCRIPTION

PIN	NAME	FUNCTION
1	VIN	Power Input. The absolute maximum input voltage is 26.5V. A 1µF or larger value X5R ceramic capacitor is recommended to be placed very close to the input pin for decoupling purpose. Additional capacitance may be required to provide a stable input voltage.
2	PPR	Open-Drain Power Presence Indication. The open-drain MOSFET turns on when the input voltage is above the POR threshold but below the OVP threshold and off otherwise. This pin is capable to sink 15mA current to drive an LED. The maximum voltage rating for this pin is 5.5V. This pin is independent on the \overline{EN} pin input.
3	CHG	Open-Drain Charge Indication. This pin outputs a logic low when a charge cycle starts and turns to high impedance when the full-of-charge (FOC) condition is qualified. This pin is capable to sink 15mA current to drive an LED. When the charger is disabled, the \overline{CHG} pin outputs high impedance.
4	ĒN	Enable Input. This is a logic input pin to disable or enable the charger. Drive to high to disable the charger. When this pin is driven to low or left floating, the charger is enabled. This pin has an internal $200 k\Omega$ pull-down resistor.
5	GND	System Ground.
6	IMIN	Full-of-Charge (FOC) Current Programming Pin. Connect a resistor between this pin and the GND pin to set the FOC current. The FOC current I _{MIN} can be programmed by the following equation: $I_{MIN} = \frac{10960}{R_{IMIN}} (mA)$ where R _{IMIN} is in kΩ.
7	IREF	Charge-Current Programming and Monitoring Pin. Connect a resistor between this pin and the GND pin to set the charge current limit determined by the following equation: $I_{REF} = \frac{11980}{R_{IREF}} + 0.6 (mA)$ where R _{IREF} is in k Ω . The resistor should be located very close to this pin. The IREF pin voltage also monitors the actual charge current during the entire charge cycle, including the trickle, constant-current, and constant-voltage phases. When disabled, V _{IREF} = 0V.
8	BAT	Charger Output Pin. Connect this pin to the battery. A 1μ F or larger X5R ceramic capacitor is recommended for decoupling and stability purposes. When the \overline{EN} pin is pulled to logic high, the BAT output is disabled.



ELECTRICAL CHARACTERISTICS

(V_{IN} = 5V, R_{IMIN} = 3M\Omega, T_A = +25 ^{\circ}C, unless otherwise noted.)

PARAM	IETER	SYMBOL	CONDIT	TIONS	MIN	TYP	MAX	UNITS
POWER-ON RESET								
Rising POR Thresho	old		V _{BAT} = 3.0V, R _{IREF} = 602	²kΩ,	3.21	3.95	4.55	V
Falling POR Thresho	old	V _{POR}	use PPR to indicate the	e comparator output.	2.86	3.60	4.35	V
VIN-BAT OFFSET V	OLTAGE	•			•	•		
Rising Edge	Rising Edge		V_{BAT} forced to 4.5V, R_{IR}	$_{\rm FF} = 602 k\Omega$, use $\overline{\rm PPR}$		110	200	mV
Falling Edge		V _{os}	pin to indicate the comp	parator output. ⁽¹⁾	5	60		mV
OVER-VOLTAGE P	ROTECTION		·		•	•		
Over-Voltage Protection Threshold		V _{OVP}	V _{BAT} forced to 4.4V, R _{IR}	_{FF} = 602kΩ,	9.35	10.50	11.15	V
		VOVPHYS	use PPR to indicate the comparator output.		245	340	430	mV
STANDBY CURREN	NT	•			•	•		
			The input is floating			0.1	0.6	μA
BAT Pin Sink Current		ISTANDBY	Charger disabled			0.2	1	μA
VIN Pin Supply Current		I _{VIN}	V_{BAT} forced to 4.4V, R_{IREF} = 301k Ω	charger disabled		180	250	μA
				charger enabled		250	320	μA
VOLTAGE REGULA	TION	•			•	•		
	SGM40561-4.2		$R_{IREF} = 301k\Omega$, $V_{IN} = 5V$, charge current = 3mA		4.152	4.2	4.248	V
Output Voltage	SGM40561-4.3	V _{CH}			4.252	4.3	4.348	V
	SGM40561-4.35				4.302	4.35	4.398	V
CHARGE CURREN	T ⁽²⁾	•	•		•	•		
IREF Pin Output Vol	tage	VIREF	V_{BAT} = 3.8V, R_{IREF} = 602k Ω		1.162	1.21	1.262	V
Constant Charge Cu	irrent	I _{REF}	R _{IREF} = 301kΩ, V _{BAT} = 3.8V		34	40	46	mA
Trickle Charge Curre	ent	I _{TRK}	R _{IREF} = 301kΩ, V _{BAT} = 2.4V		3.5	7.5	11.5	mA
Full-of-Charge Curre	ent	I _{MIN}	$R_{IREF} = 301 k\Omega$		1	4	7	mA
FOC Rising Thresho	ld		R _{IREF} = 301kΩ		22	31	40	mA
PRECONDITIONING	G CHARGE THRESH	IOLD	•		•	•		
Preconditioning	SGM40561-4.2					2.55		V
Charge Threshold	SGM40561-4.3	V _{MIN}	$R_{IREF} = 60.4 k\Omega$			2.62		V
Voltage	SGM40561-4.35	1				2.65		V
Preconditioning Volt	age Hysteresis	V _{MINHYS}	R _{IREF} = 60.4kΩ			100		mV
INTERNAL TEMPE	RATURE MONITOR	ING			•	•	•	
Charge Current Fold	back Threshold	T _{FOLD}				115		°C

NOTES:

1. The 4.5V V_{BAT} is selected so that the \overline{PPR} output can be used as the indication for the offset comparator output indication. If the V_{BAT} is lower than the POR threshold, no output pin can be used for indication.

2. The charge current may be affected by the thermal foldback function.



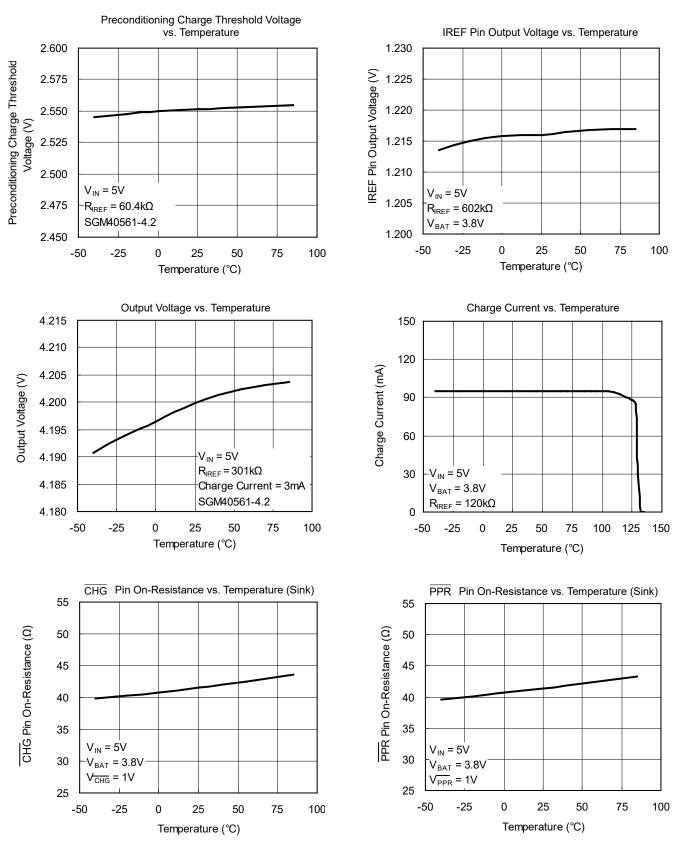
ELECTRICAL CHARACTERISTICS (continued)

 $(V_{IN} = 5V, R_{IMIN} = 3M\Omega, T_A = +25^{\circ}C, unless otherwise noted.)$

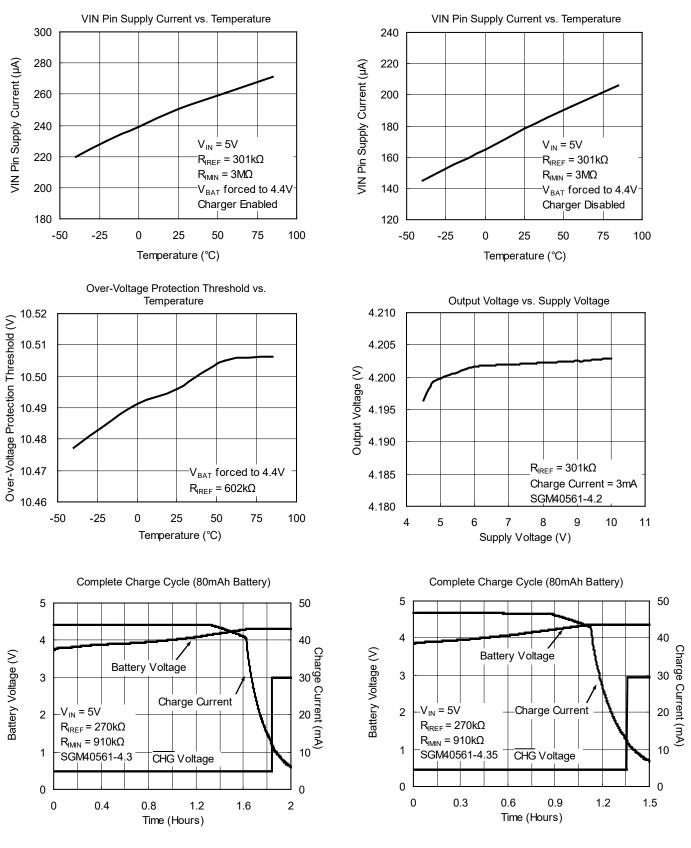
PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
LOGIC INPUT AND OUTPUTS						
EN Pin Logic Input High			1.6			V
EN Pin Logic Input Low					0.8	V
EN Pin Internal Pull-Down Resistance			150	200	250	kΩ
CHG Pin On-Resistance when LOW		Pin voltage = 1V		42	67	Ω
CHG Leakage Current when High Impedance		V _{CHG} = 5.5V			4.5	μA
PPR Pin On-Resistance when LOW		Pin voltage = 1V		42	67	Ω
PPR Leakage Current when High Impedance Impedance		V _{PPR} = 5.5V			4.5	μA



TYPICAL PERFORMANCE CHARACTERISTICS

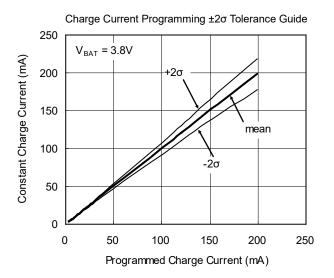


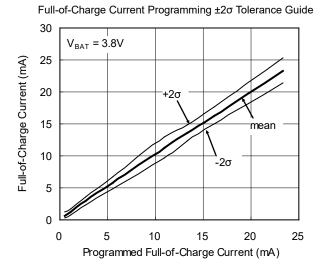
TYPICAL PERFORMANCE CHARACTERISTICS (continued)



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TYPICAL PERFORMANCE CHARACTERISTICS (continued)







TYPICAL APPLICATION CIRCUITS

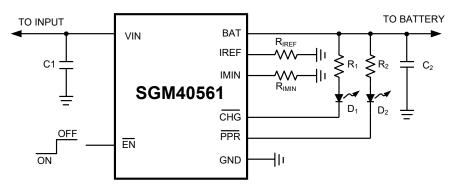


Figure 1. Typical Application Circuit Interfacing to Indication LEDs

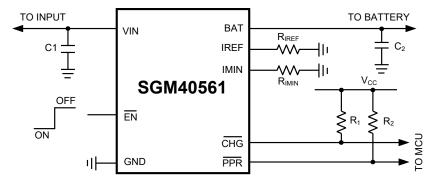


Figure 2. Typical Application Circuit with the Indication Signals Interfacing to an MCU

COMPONENT DESCRIPTION FOR Figure 1

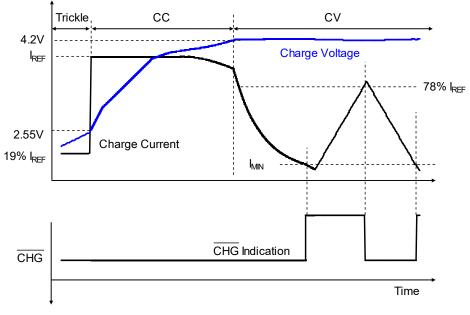
PART	DESCRIPTION
C ₁	1µF X5R ceramic cap
C ₂	1µF X5R ceramic cap
RIREF	301k Ω , for 40mA charge current
R IMIN	3MΩ, for 4mA FOC current
D ₁ , D ₂	LEDs for indication

COMPONENT DESCRIPTION FOR Figure 2

PART	DESCRIPTION
C ₁	1µF X5R ceramic cap
C ₂	1µF X5R ceramic cap
RIREF	301k Ω , for 40mA charge current
RIMIN	3MΩ, for 4mA FOC current
R ₁ , R ₂	100kΩ, 5%



TYPICAL APPLICATION CIRCUITS (continued)





FUNCTIONAL BLOCK DIAGRAM

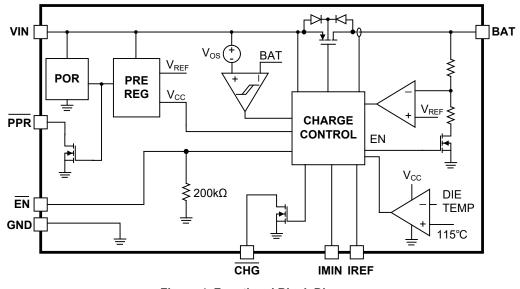


Figure 4. Functional Block Diagram

SGM40561

OPERATION

The SGM40561 charges a Li-lon battery using a CC/CV profile. The constant current I_{REF} is set with the external resistor R_{IREF} (see Figure 1) and the constant voltage is fixed at 4.2V, 4.3V or 4.35V. If the battery voltage is below a typical 2.55V, 2.62V or 2.65V trickle charge threshold, the SGM40561 charges the battery with a trickle current of 19% of IREF until the battery voltage rises above the trickle charge threshold. Fast charge CC mode is maintained at the rate determined by programming I_{RFF} until the cell voltage rises to 4.2V, 4.3V or 4.35V. When the battery voltage reaches 4.2V, 4.3V or 4.35V, the charger enters a CV mode and regulates the battery voltage at 4.2V, 4.3V or 4.35V to fully charge the battery without the risk of over charge. Upon reaching an full-of-charge (FOC) current, the charger indicates the charge completion with the CHG pin, but the charger continues to output the 4.2V, 4.3V or 4.35V voltage. Figure 3 shows the typical charge waveforms after the power is on.

The FOC current level I_{MIN} is programmable with the external resistor R_{IMIN} (see Figure 1). The \overline{CHG} pin turns to low when the trickle charge starts and rises to high impedance at the FOC. After the FOC is reached, the charge current has to rise to typically 78% of I_{REF} for the \overline{CHG} pin to turn on again, as shown in Figure 3. The current surge after FOC can be caused by a load connected to the battery.

A thermal foldback function reduces the charge current anytime when the die temperature reaches typically 115°C. This function guarantees safe operation when the printed circuit board (PCB) is not capable of dissipating the heat generated by the linear charger. The SGM40561 accepts an input voltage up to 26.5V but disables charging when the input voltage exceeds the OVP threshold, typically 10.5V, to protect against unqualified or faulty AC adapters.

PPR Indication

The \overline{PPR} pin is an open-drain output to indicate the presence of the AC adapter. Whenever the input voltage is higher than the POR threshold, the \overline{PPR} pin turns on the internal open-drain MOSFET to indicate a logic low signal, independent on the \overline{EN} pin input. When the internal open-drain FET is turned off, the \overline{PPR} pin leaks less than 4.5µA current. When turned

on, the \overrightarrow{PPR} pin is able to sink at least 15mA current under all operating conditions. The \overrightarrow{PPR} pin can be used to drive an LED (see Figure 1) or to interface with a micro- processor.

Power Good Range

The power good range is defined by the following three conditions:

1. V_{IN} > V_{POR} 2. V_{IN} - V_{BAT} > V_{OS} 3. V_{IN} < V_{OVP}

where the V_{OS} is the offset voltage for the input and output voltage comparator, discussed shortly, and the V_{OVP} is the over-voltage protection threshold given in the Electrical Characteristics table. All V_{POR} , V_{OS} , and V_{OVP} have hysteresis, as given in the Electrical Characteristics table. The charger will not charge the battery if the input voltage is not in the power good range.

Input and Output Comparator

The charger will not be enabled unless the input voltage is higher than the battery voltage by an offset voltage V_{OS} . The purpose of this comparator is to ensure that the charger is turned off when the input power is removed from the charger. Without this comparator, it is possible that the charger will fail to power down when the input is removed and the current can leak through the PFET pass element to continue biasing the POR and the Pre-Regulator blocks.

Dropout Voltage

The constant current may not be maintained due to the $R_{DS(ON)}$ limit at a low input voltage. The worst case $R_{DS(ON)}$ is at the maximum allowable operating temperature.

CHG Indication

The \overline{CHG} is an open-drain output capable of sinking at least 15mA current when the charger starts to charge, and turns off when the FOC current is reached. The \overline{CHG} signal is interfaced either with a microprocessor GPIO or an LED for indication.



OPERATION (continued)

EN Input

 \overline{EN} is an active-low logic input to enable the charger. Drive the \overline{EN} pin to low or leave it floating to enable the charger. This pin has a 200k Ω internal pull-down resistor so when left floating, the input is equivalent to logic low. Drive this pin to high to disable the charger. The threshold for high is given in the Electrical Characteristics table.

IREF Pin

The IREF pin has the two functions as described in the Pin Description section. When monitoring the charge current, the accuracy of the IREF pin voltage vs. the actual charge current has the same accuracy as the gain from the IREF pin current to the actual charge current.

Operation without the Battery

The SGM40561 relies on a battery for stability and works under LDO mode if the battery is not connected. With a battery, the charger will be stable with an output ceramic decoupling capacitor in the range of 1μ F to 200 μ F. In LDO mode, its stability depends on load current, C_{OUT}, etc. The maximum load current is limited by the dropout voltage, the programmed I_{REF} and the thermal foldback.

Thermal Foldback

The thermal foldback function starts to reduce the charge current when the internal temperature reaches a typical value of 115° C.



APPLICATION INFORMATION

Design of IREF, IMIN and CHG Indication

A higher I_{REF} charges quicker, at the penalty of reduced battery life. The maximum I_{REF} should be designed to follow battery vendor's instruction for a given battery life expectation.

 I_{MIN} is the end of charge current when \overline{CHG} indicates a full of charge condition. All current out of the SGM40561 BAT pin should be counted into I_{MIN} , including load current and the indication LED currents. As illustrated in Figure 3, the SGM40561 continues to supply current unless it is disabled by \overline{EN} pulled high, regardless of the status of \overline{CHG} pin. When charge current ever goes lower than I_{MIN} , \overline{CHG} pin stays high impendence until the charge current goes higher than 78% of I_{REF} , which is another factor to consider in design of I_{REF} , I_{REF} should be high enough to so that 78% of I_{REF} is higher than the current that is designed not to initiate \overline{CHG} indication, while is low enough to assure the power source could deliver higher than 78% of I_{REF} to initiate \overline{CHG} indication.

Input Capacitor Selection

The input capacitor is required to suppress the power supply transient response during transitions. Mainly this capacitor is selected to avoid oscillation during the start up when the input supply is passing the POR threshold and the VIN-BAT comparator offset voltage. When the battery voltage is above the POR threshold, the V_{IN} - V_{BAT} offset voltage dominates the hysteresis value. Typically, a 1µF X5R ceramic capacitor should be sufficient to suppress the power supply noise.

Output Capacitor Selection

The criterion for selecting the output capacitor is to maintain the stability of the charger as well as to bypass any transient load current. The minimum capacitance is a 1μ F X5R ceramic capacitor. The actual capacitance connected to the output is dependent on the actual application requirement.

Layout Guidance

The SGM40561 uses thermally-enhanced TDFN package that has an exposed thermal pad at the bottom side of the package. The layout should connect as much as possible to copper on the exposed pad. Typically the component layer is more effective in dissipating heat. The thermal impedance can be further reduced by using other layers of copper connecting to the exposed pad through a thermal via array. Each thermal via is recommended to have 0.3mm diameter and 1mm distance from other thermal vias.

REVISION HISTORY

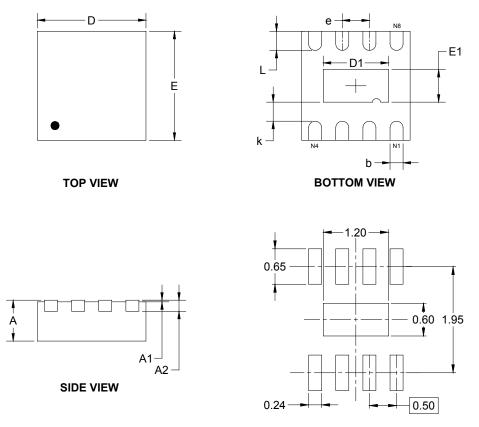
NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

OCTOBER 2017 - REV.A.2 to REV.A.3

Changed Electrical Characteristics section	
APRIL 2017 – REV.A.1 to REV.A.2	
Changed Absolute Maximum Ratings section	2
OCTOBER 2016 – REV.A to REV.A.1	
Changed Electrical Characteristics section	4
Changes from Original (SEPTEMBER 2015) to REV.A	
Changed from product preview to production data	All
SG Micro Corp	OCTOBER 2017

PACKAGE OUTLINE DIMENSIONS

TDFN-2×2-8L



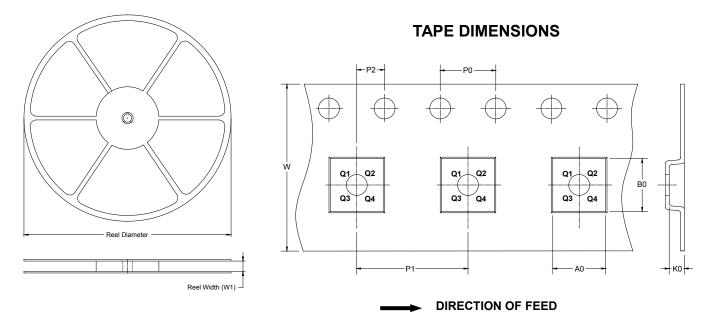
RECOMMENDED LAND PATTERN (Unit: mm)

Symbol		nsions meters	Dimensions In Inches		
	MIN	MAX	MIN	MAX	
А	0.700	0.800	0.028	0.031	
A1	0.000	0.050	0.000	0.002	
A2	0.203	B REF	0.008 REF		
D	1.900	2.100	0.075	0.083	
D1	1.100	1.300	0.043	0.051	
E	1.900	2.100	0.075	0.083	
E1	0.500	0.700	0.020	0.028	
k	0.200) MIN	300.0	3 MIN	
b	0.180	0.300	0.007	0.012	
е	0.500 TYP		0.020) TYP	
L	0.250	0.450	0.010	0.018	



TAPE AND REEL INFORMATION

REEL DIMENSIONS

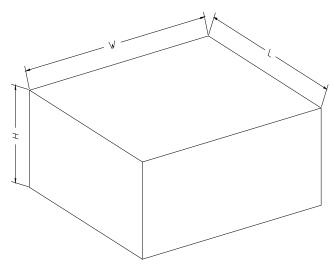


NOTE: The picture is only for reference. Please make the object as the standard.

KEY PARAMETER LIST OF TAPE AND REEL

Package Type	Reel Diameter	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P0 (mm)	P1 (mm)	P2 (mm)	W (mm)	Pin1 Quadrant
TDFN-2×2-8L	7″	9.5	2.30	2.30	1.10	4.0	4.0	2.0	8.0	Q1

CARTON BOX DIMENSIONS



NOTE: The picture is only for reference. Please make the object as the standard.

KEY PARAMETER LIST OF CARTON BOX

Reel Type	Length (mm)	Width (mm)	Height (mm)	Pizza/Carton	
7" (Option)	368	227	224	8	
7"	442	410	224	18	00002

